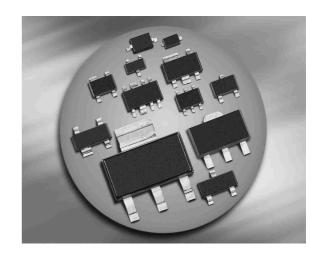


Silicon Schottky Diodes

- For low-loss, fast-recovery, meter protection, bias isolation and clamping application
- Guard ring protected
- Low forward voltage
- Pb-free (RoHS compliant) package
- Qualified according AEC Q1011)





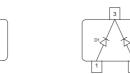


| BAI | 54-02LRH |
|------------|----------|
| BAT | 54-02V |
| BAT | 54-03W |



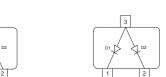
BAT54





BAT54-05

BAT54-05W



BAT54-06

BAT54-06W

| Туре | Package | Configuration | L _S (nH) | Marking |
|--------------|----------|----------------|----------------------------|---------|
| BAT54 | SOT23 | single | 1.8 | Т |
| BAT54-02LRH* | TSLP-2-7 | single | 0.4 | 54 |
| BAT54-02V | SC79 | single | 0.6 | b |
| BAT54-03W | SOD323 | single | 1.8 | blue 5 |
| BAT54-04 | SOT23 | series | 1.8 | TS |
| BAT54-04W | SOT323 | series | 1.4 | TS |
| BAT54-05 | SOT23 | common cathode | 1.8 | TC |
| BAT54-05W | SOT323 | common cathode | 1.4 | TC |
| BAT54-06 | SOT23 | common anode | 1.8 | TA |
| BAT54-06W | SOT323 | common anode | 1.4 | TA |
| BAT54W | SOT323 | single | 1.4 | T5 |

1

BAT54-04

^{1*}BAT54-02LRH is not qualified according AEC Q101



Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

| Parameter | Symbol | Value | Unit |
|---|------------------|---------|------|
| Diode reverse voltage | V_{R} | 30 | V |
| Forward current | / _F | 200 | mA |
| Non-repetitive peak surge forward current | / _{FSM} | 600 | |
| $(t \le 10 \text{ ms})$ | | | |
| Repetitive peak forward current ¹⁾ | / _{FRM} | 300 | mA |
| $t_{p} \leq 1 \; s, \; \delta = 0.5$ | | | |
| Total power dissipation | P _{tot} | | mW |
| BAT54, <i>T</i> _S ≤ 94 °C | | 230 | |
| BAT54-02LRH, <i>T</i> _S ≤ 135 °C | | 230 | |
| BAT54-02V, <i>T</i> _S ≤ 126 °C | | 230 | |
| BAT54-03W, <i>T</i> _S ≤ 122 °C | | 230 | |
| BAT54-04, <i>T</i> _S ≤ 71 °C | | 230 | |
| BAT54-04W, <i>T</i> _S ≤ 117 °C | | 230 | |
| BAT54-05, <i>T</i> _S ≤ 48 °C | | 230 | |
| BAT54-05W, <i>T</i> _S ≤ 110 °C | | 230 | |
| BAT54-06, <i>T</i> _S ≤ 71 °C | | 230 | |
| BAT54-06W, <i>T</i> _S ≤ 117 °C | | 230 | |
| BAT54W, <i>T</i> _S ≤ 125 °C | | 230 | |
| Junction temperature | T_{j} | 150 | °C |
| Storage temperature | T _{stg} | -65 150 | |

 $^{^{1}}$ Device mounted on epoxy PCB 40 x 40 x 1.5 mm / 6 cm 2 Cu



Thermal Resistance

| Parameter | Symbol | Value | Unit |
|------------------------------|------------|-------|------|
| Junction - soldering point1) | R_{thJS} | | |
| BAT54 | | ≤ 245 | |
| BAT54-02LRH | | ≤ 65 | |
| BAT54-02V | | ≤ 105 | |
| BAT54-03W | | ≤ 120 | |
| BAT54-04 | | ≤ 345 | |
| BAT54-04W | | ≤ 145 | |
| BAT54-05 | | ≤ 445 | |
| BAT54-05W | | ≤ 175 | |
| BAT54-06 | | ≤ 345 | |
| BAT54-06W | | ≤ 145 | |
| BAT54W | | ≤ 110 | |

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

| Parameter | Symbol | | Values | | |
|---------------------------------|------------|------|--------|------|----|
| | | min. | typ. | max. | |
| DC Characteristics | | | | | |
| Breakdown voltage ²⁾ | $V_{(BR)}$ | 30 | - | - | V |
| I _(BR) = 10 μA | | | | | |
| Reverse current ²⁾ | I_{R} | - | - | 2 | μA |
| V _R = 25 V | | | | | |
| Forward voltage ²⁾ | V_{F} | | | | mV |
| $I_{\rm F}$ = 0.1 mA | | - | - | 240 | |
| / _F = 1 mA | | - | - | 320 | |
| I _F = 10 mA | | - | - | 400 | |
| $I_{\rm F}$ = 30 mA | | - | - | 500 | |
| / _F = 100 mA | | - | - | 800 | |

 $^{^{\}rm 1} {\rm For}$ calculation of $R_{\rm thJA}$ please refer to Application Note Thermal Resistance

²Pulsed test: t_p = 300 µs; D = 0.01



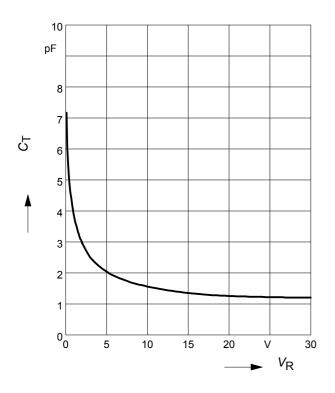
Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

| Parameter | Symbol | | Unit | | |
|---|----------------|------|------|------|----|
| | | min. | typ. | max. | |
| AC Characteristics | | | | | |
| Diode capacitance | C _T | - | - | 10 | pF |
| $V_{R} = 1 \text{ V}, f = 1 \text{ MHz}$ | | | | | |
| Reverse recovery time | t_{rr} | - | - | 5 | ns |
| $I_{\rm F}$ = 10 mA, $I_{\rm R}$ = 10 mA, measured $I_{\rm R}$ = 1 mA , | | | | | |
| R_{L} = 100 Ω | | | | | |



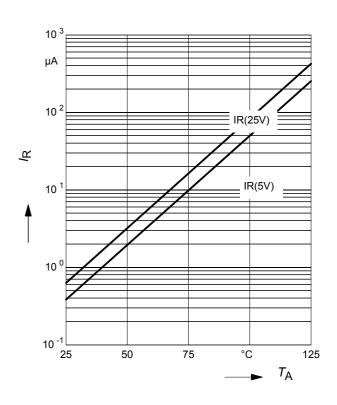
Diode capacitance $C_T = f(V_R)$

f = 1MHz



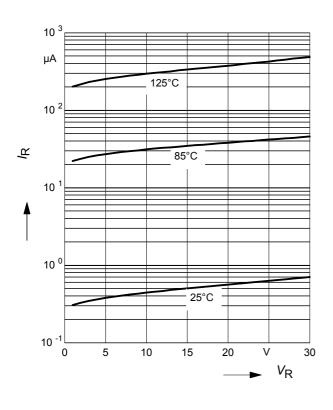
Reverse current $I_R = f(T_A)$

 V_{R} = Parameter



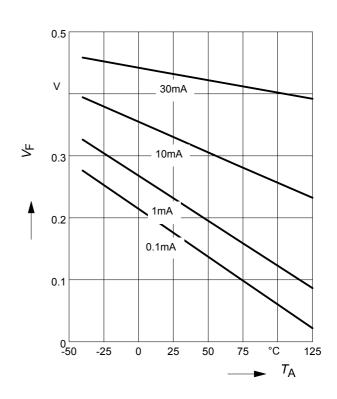
Reverse current $I_R = f(V_R)$

 T_A = Parameter



Forward Voltage $V_F = f(T_A)$

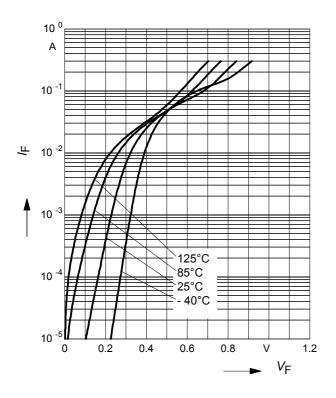
 I_{F} = Parameter





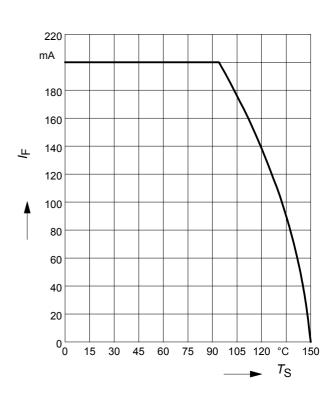
Forward current $I_F = f(V_F)$

 T_A = Parameter



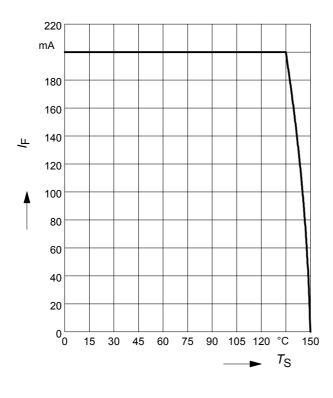
Forward current $I_F = f(T_S)$

BAT54



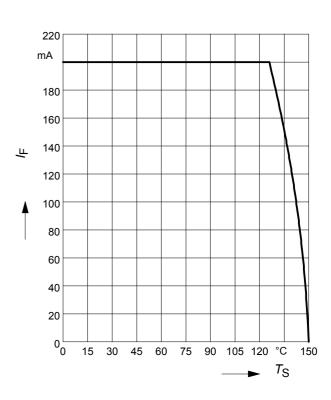
Forward current $I_F = f(T_S)$

BAT54-02LRH



Forward current $I_F = f(T_S)$

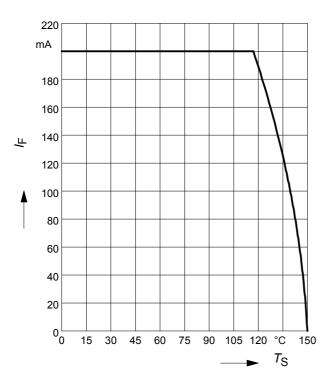
BAT54-02V





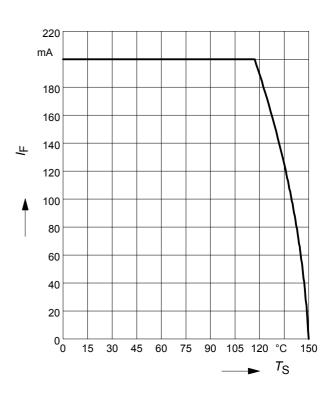
Forward current $I_F = f(T_S)$

BAT54-04



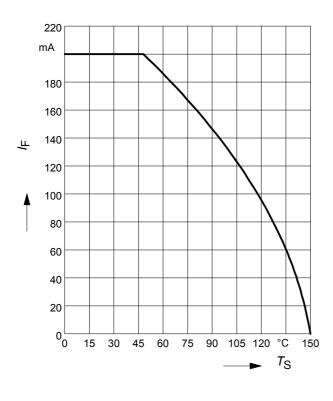
Forward current $I_F = f(T_S)$

BAT54-04W



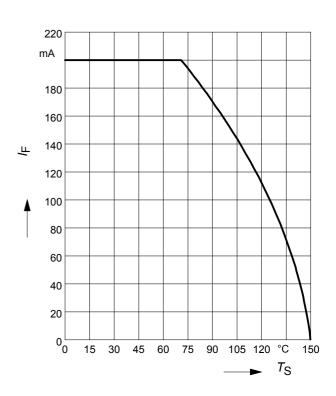
Forward current $I_F = f(T_S)$

BAT54-05



Forward current $I_F = f(T_S)$

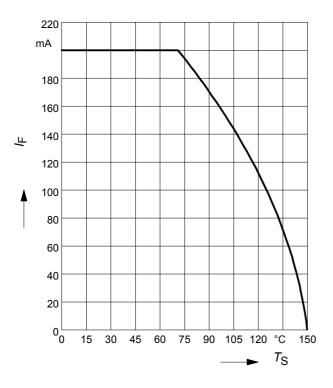
BAT54-05W





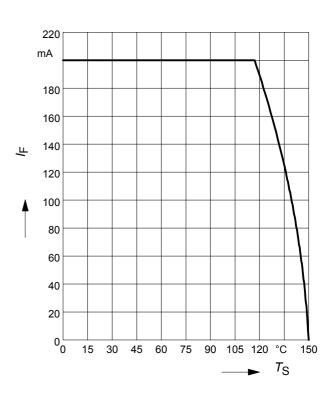
Forward current $I_F = f(T_S)$

BAT54-06



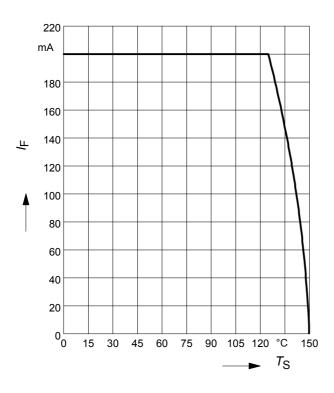
Forward current $I_F = f(T_S)$

BAT54-06W



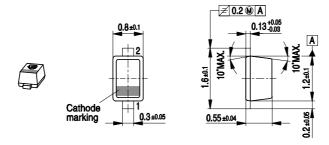
Forward current $I_F = f(T_S)$

BAT54W



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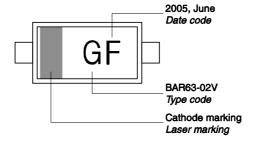




Foot Print



Marking Layout (Example)

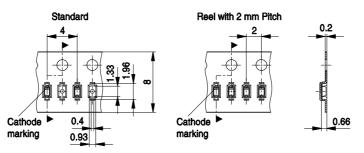


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel



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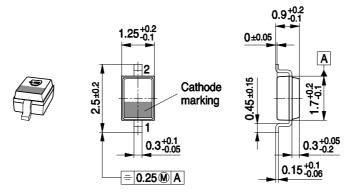
Date Code marking for discrete packages with one digit (SCD80, SC79, SC751) CES-Code

| Month | 2003 | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|
| 01 | а | р | Α | Р | а | р | Α | Р | а | р | Α | Р |
| 02 | b | q | В | Q | b | q | В | Q | b | q | В | Q |
| 03 | С | r | С | R | С | r | С | R | С | r | С | R |
| 04 | d | s | D | S | d | s | D | S | d | s | D | S |
| 05 | е | t | Е | T | е | t | Е | Т | е | t | Е | Т |
| 06 | f | u | F | U | f | u | F | U | f | u | F | U |
| 07 | g | ٧ | G | V | g | ٧ | G | V | g | ٧ | G | V |
| 08 | h | Х | Н | Х | h | Х | Н | Χ | h | Х | Н | Х |
| 09 | j | У | J | Υ | j | У | J | Υ | j | У | J | Υ |
| 10 | k | Z | K | Z | k | Z | K | Z | k | Z | K | Z |
| 11 | I | 2 | L | 4 | I | 2 | L | 4 | I | 2 | L | 4 |
| 12 | n | 3 | N | 5 | n | 3 | N | 5 | n | 3 | N | 5 |

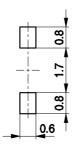
¹⁾ New Marking Layout for SC75, implemented at October 2005.

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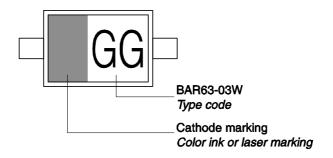




Foot Print

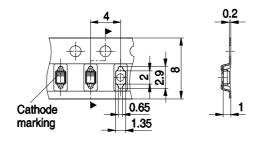


Marking Layout (Example)

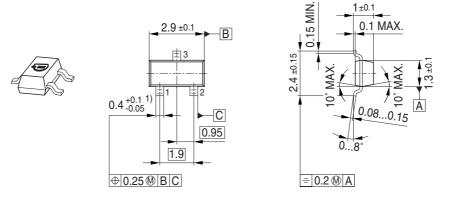


Standard Packing

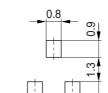
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





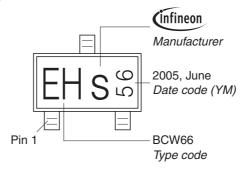


Foot Print



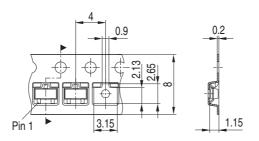
1) Lead width can be 0.6 max. in dambar area

Marking Layout (Example)



Standard Packing

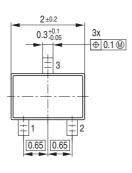
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

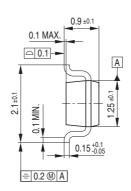


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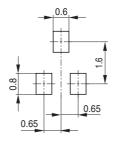




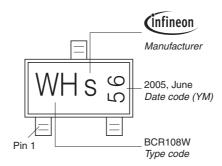




Foot Print

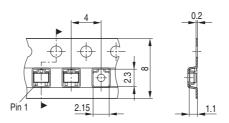


Marking Layout (Example)

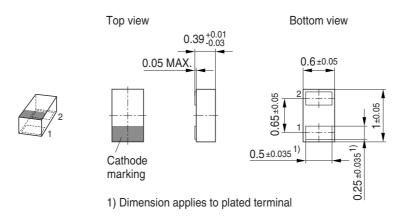


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

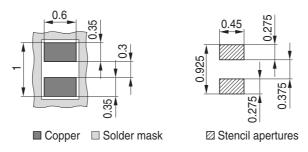




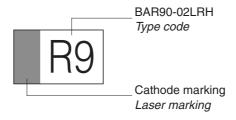


Foot Print

For board assembly information please refer to Infineon website "Packages"

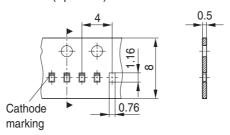


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)



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